

Title (en)

PROCESS FOR THE MANUFACTURE OF PRINTED CIRCUIT BOARDS WITH PLATED RESISTORS

Title (de)

PROZESS ZUR HERSTELLUNG VON LEITERPLATTEN MIT PLATTIERTEN WIDERSTÄNDEN

Title (fr)

PROCEDE DE FABRICATION DE CARTES DE CIRCUITS IMPRIMES A RESISTANCES METALLISEES

Publication

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Application

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Priority

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Abstract (en)

[origin: WO02066256A2] A process is revealed whereby resistors can be manufactured integral with a printed circuit board by plating the resistors onto the insulative substrate. Uniformization of the insulative substrate through etching and oxidation of the plated resistor are discussed as techniques for improving the uniformity and consistency of the plated resistors. Trimming and baking are also disclosed as methods for adjusting and stabilizing the resistance of the plated resistors.

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